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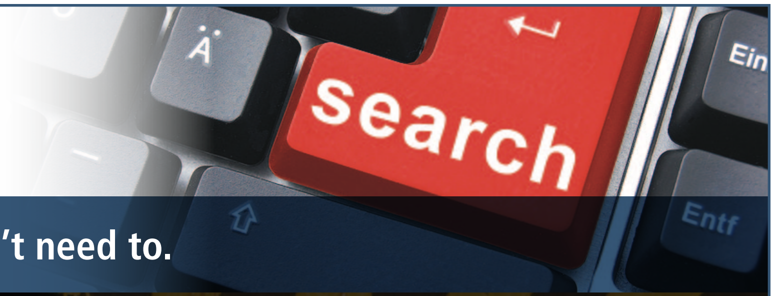

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Electronic-media continues to expand as industry professionals seek daily updates on news and events shaping the semiconductor packaging and micro-electronics market. An advertising campaign in Semiconductor Packaging News provides daily e-media visibility with high-frequency advertising designed to meet every budget. We reach over 230,000 industry professionals who are eager to learn more about your products and services.

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- White papers hosted at no cost & provide contact names and e-mail address
- Corporate press releases published daily
- Exclusive articles and interviews from industry events
- Company events posted in the event calendar

Analytical Data

Recent analytical data collected from an independent company confirms our readership continues to expand. Semiconductor Packaging News e-mail newsletter is broadcast to over 35,000 opt-in subscribers every business day.

During the past 12-months SPN has reached over 230,000 unique visitors from 125 countries. The e-mail newsletter subscriber base is always up-to-date and is managed by an independent e-mail management company.

Top 10 markets by geographic readership:

- North America
- Singapore
- South Korea
- Japan
- Taiwan
- Germany
- France
- China
- Malaysia
- Netherlands

Demographics by region of the world:
45% Americas, 33% Asia Pacific, and 22% Europe

SEMI, MEPTEC, IMAPS, IEEE and other industry organizations partner with Semiconductor Packaging News to reach their members and drive visitors to their events and trade shows.

Comments from several Semiconductor Packaging News advertisers:

"SPN provides a great opportunity to reach a range of prospects on a daily basis for a very competitive price. We can advertise for an entire year for the cost of a small booth at a local show".
J.B.

"The White Paper program in SPN has delivered hundreds of prospects from around the world. This is a great way to reach new customers".
R.H.

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R.B.

"Semiconductor Packaging allows us to reach our markets around the globe. We book new orders from readers of SPN".
J.F.

"In this period of decline in print publications, our users are turning to the internet as the source of information. We have benefited from our aggressive use of SPN as advertising vehicles".
R.B.

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Semiconductor Packaging News Readers

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Over 35,000 daily subscribers find Semiconductor Packaging News to be their go-to source for news and information in the semi and mico-electronics assembly market. Semiconductor Packaging News subscribers and website visitors are the industry professionals you want to reach; they're your prospects and your customers.

Rather than waiting for the monthly issue of their favorite trade publication, these are professionals who every day have a need to know – and who bear the responsibility for looking ahead, thinking, and imagining the future to keep their companies on top! They keep themselves up to speed by reading Semiconductor Packaging News. Over 500,000 articles have been clicked and read by Semiconductor Packaging News readers.

Based on a readership survey we are proud to share data and commentary from industry professionals who took part in our survey.

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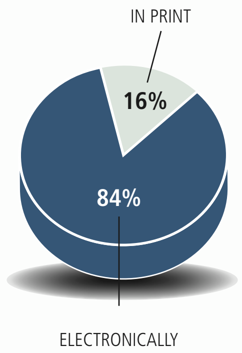
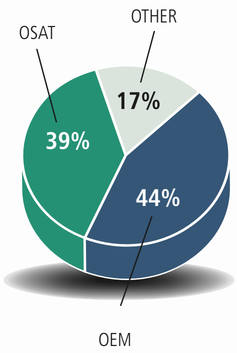


Company Type



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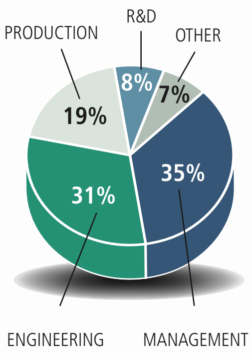

Comments from several Semiconductor Packaging News subscribers/readers:

"Semiconductor Packaging News is the only daily newsletter focused on the packaging side of the industry".

"SPN is the best daily newsletter, I look forward to reading each day".

"This is the best daily newsletter for insight on the micro-electronics and semiconductor industries."

"I read SPN regularly and find the mix of information to be quite interesting".

"As an Asia Pacific reader, I find your newsletter useful to gain the global perspective on the growing 3D packaging".

"All the important news in one place, great way to start my morning".

Nice Job.. really stands out..very newsy with lots of good stuff.

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Advertising Opportunities

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Semiconductor Packaging News advertising delivers results. We deliver your message to the largest readership with the highest frequency. Ad campaigns in Semiconductor Packaging News provide more visibility of your message compared to other newsletters and print media. The more often your ads run, the more response you will receive.

Banner Ads

Banner Ads are ideal for branding with corporate colors and a company logo. Large banner ads (160 x 300 pixels and 468 x 60 pixels) provide significant space to deliver your messages for maximum exposure.

Text Ads

A well written text ad will intrigue the reader to click the ad to learn more about your product or service. The goal of a text ad is to deliver readers directly to your website. We encourage our advertisers to run multiple text ads in a single ad campaign at no extra cost.

Did You Know: Text ads will typically deliver 4 times as many clicks as a banner ad.Many ad campaigns combine both banner and text ads alternating through the month. Advertisers use banner ads to build their company brand and text ads to drive visitors to pages on their web site.

Sponsor Positions

Gold Level advertiser text ads run at the top of the newsletter and website twice per month. Their company logo is placed on the top right column for the entire day.

White Papers

Semiconductor Packaging will host your white paper at no cost allowing readers to download them with a simple registration. Readers download over 2,000 white papers per month and we provide the name and email addresses to our advertisers at no cost.

Monthly Reports

Semiconductor Packaging News provides a monthly e-media report showing activity including clicks, impressions, press release postings, white paper downloads and calendar events. This monthly report is sent to you via e-mail allowing you to measure the success of your ad campaigns. Advertisers can monitor impressions and clicks for each ad campaign providing important data to manage the e-media program. Ads can be changed at any time to refocus their impact and we encourage you to update frequently to keep your ads fresh and engaging, all at no added cost.

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FINETECH will showcase the FINEPLACER® Lambda in Booth 2204 at the upcoming SPIE Photonics West exhibition, scheduled for January 22-27 ...

November 19, 2010
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MARTIN will demonstrate the Prebump/Reball 03.1 unit at the upcoming SMTA Arizona-Sonora Expo & Tech Forum, scheduled to take place Wednesday ...

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June 28, 2010
FINETECH to Showcase Sub-Micron Bonder at SEMICON West
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June 2, 2010
FINETECH to Showcase Sub-Micron Bonder at SEMICON West 2010
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Recent White Papers - If you are an advertiser, click "Download List" to view a list of names. — Submit a White Paper

Posted May 5, 2009
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With more competition for capital equipment dollars, it will be the equipment that offers application flexibility and value that wins the ...
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Silver Campaign
Banner ad and text ad campaigns run 8 days per month, twice per week. Ads will display in the broadcast e-mail newsletter only. This does not include website exposure.

3 month campaign $995/month,
6 month campaign $950/month,
12 month campaign $895/month
(credit card pricing)

Gold Campaign
Banner ads and text ads run 15 days per month including sponsor position twice per month with text ad and logo. Ads will be displayed in the broadcast e-mail newsletter and on the website.

3 month campaign $1950/month,
6 month campaign $1900/month,
12 month campaign $1850/month
(credit card pricing)

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About Us

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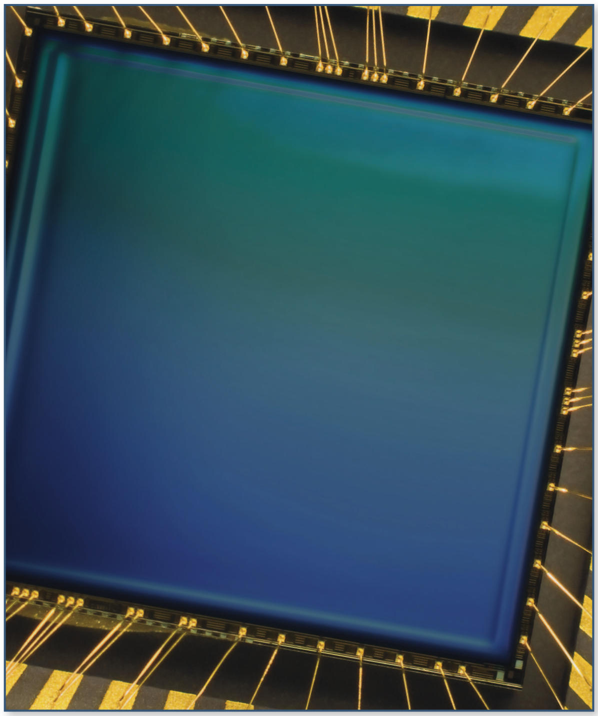
We believe it's our job to dig through the unending stream of news, articles, features, and discussions to deliver information, covering the world of semiconductor packaging and mirco-electronics, to our readers. Every month we publish links to more than 300 important industry news articles. We package this information into a convenient newsletter that we deliver to our subscribers via e-mail - every business day.

The Semiconductor Packaging Newsletter and website features links to industry and technology news stories and feature articles about the semiconductor packaging market. We publish the latest corporate and product news announcements industry company's submit to us.

We also deliver over 2,000 white paper downloads every month and we'll post your papers at no cost. You'll also find commentaries, cartoons, an industry event calendar and much more.

We look forward to working with you on your e-media campaign.



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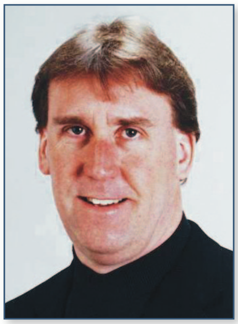

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